

ABSTRACT OF THE DISCLOSURE

A method of producing an electronic device electrically and mechanically couples an integrated circuit to a leadframe to produce an intermediate assembly. At least a portion of the intermediate assembly then is encapsulated
5 with a molten encapsulating material. After it is encapsulated, the method permits the molten encapsulating material to substantially solidify. A method of detecting the orientation of a sensor as mounted to an external object also is disclosed.